
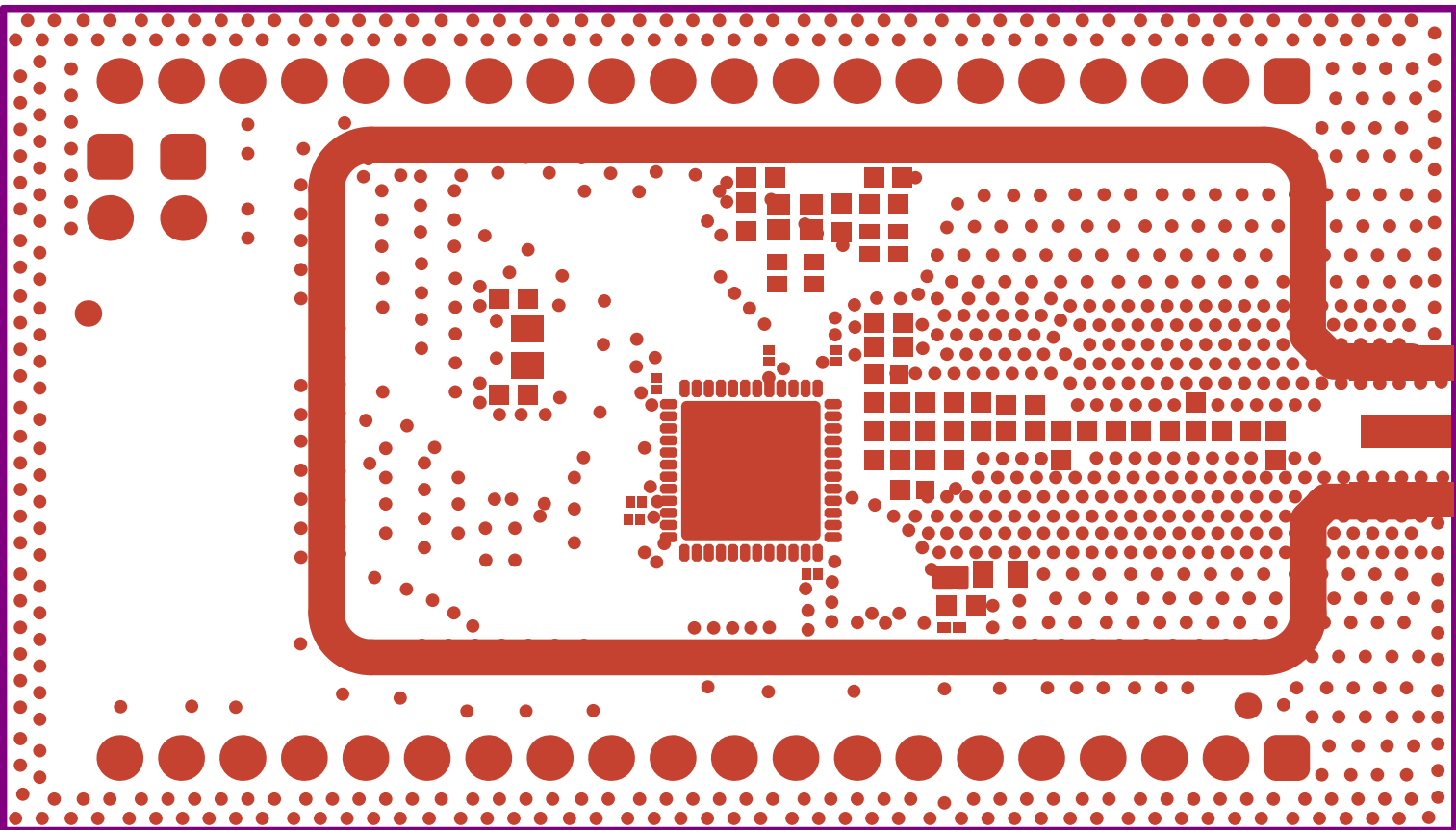

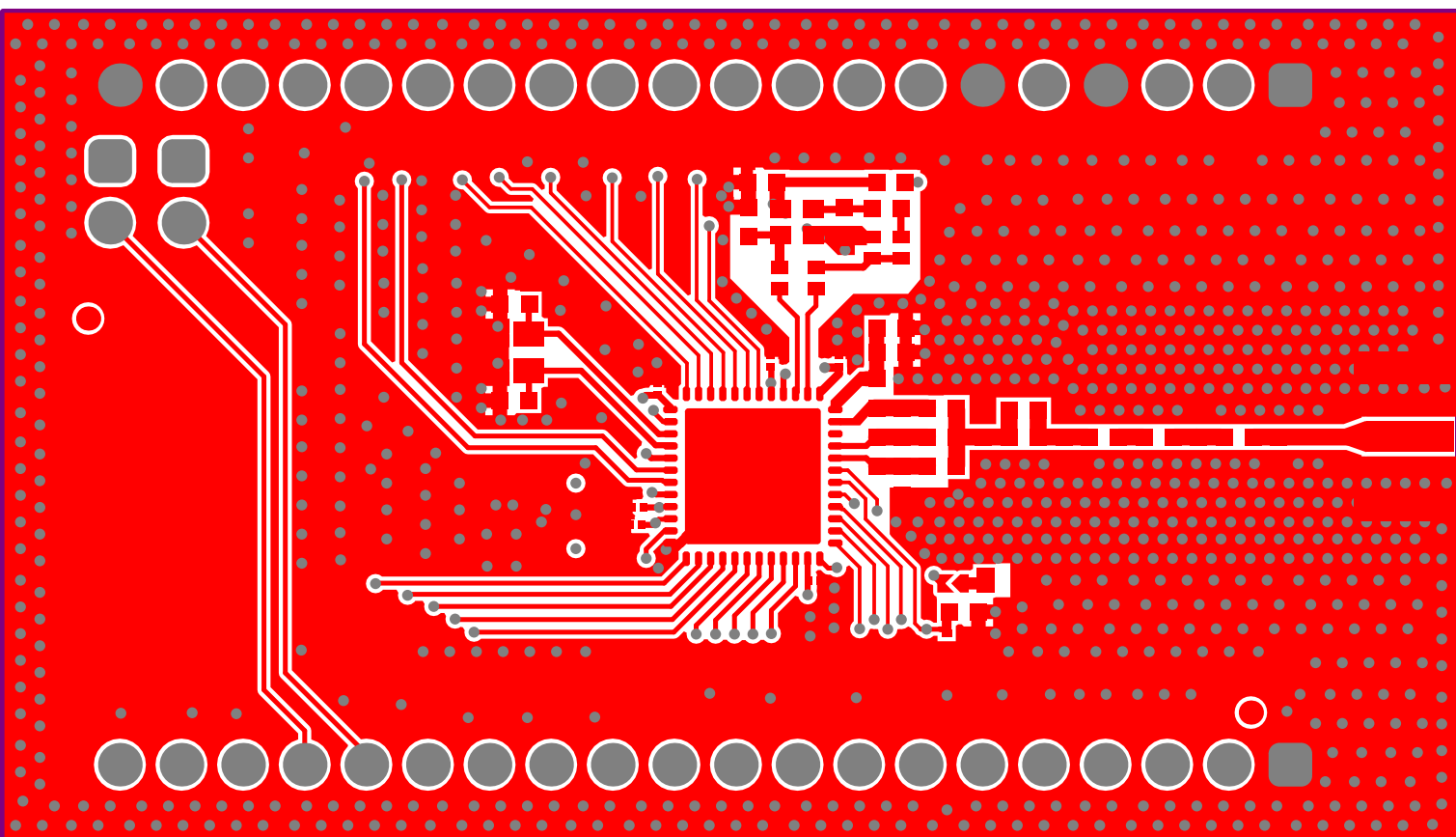



Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	

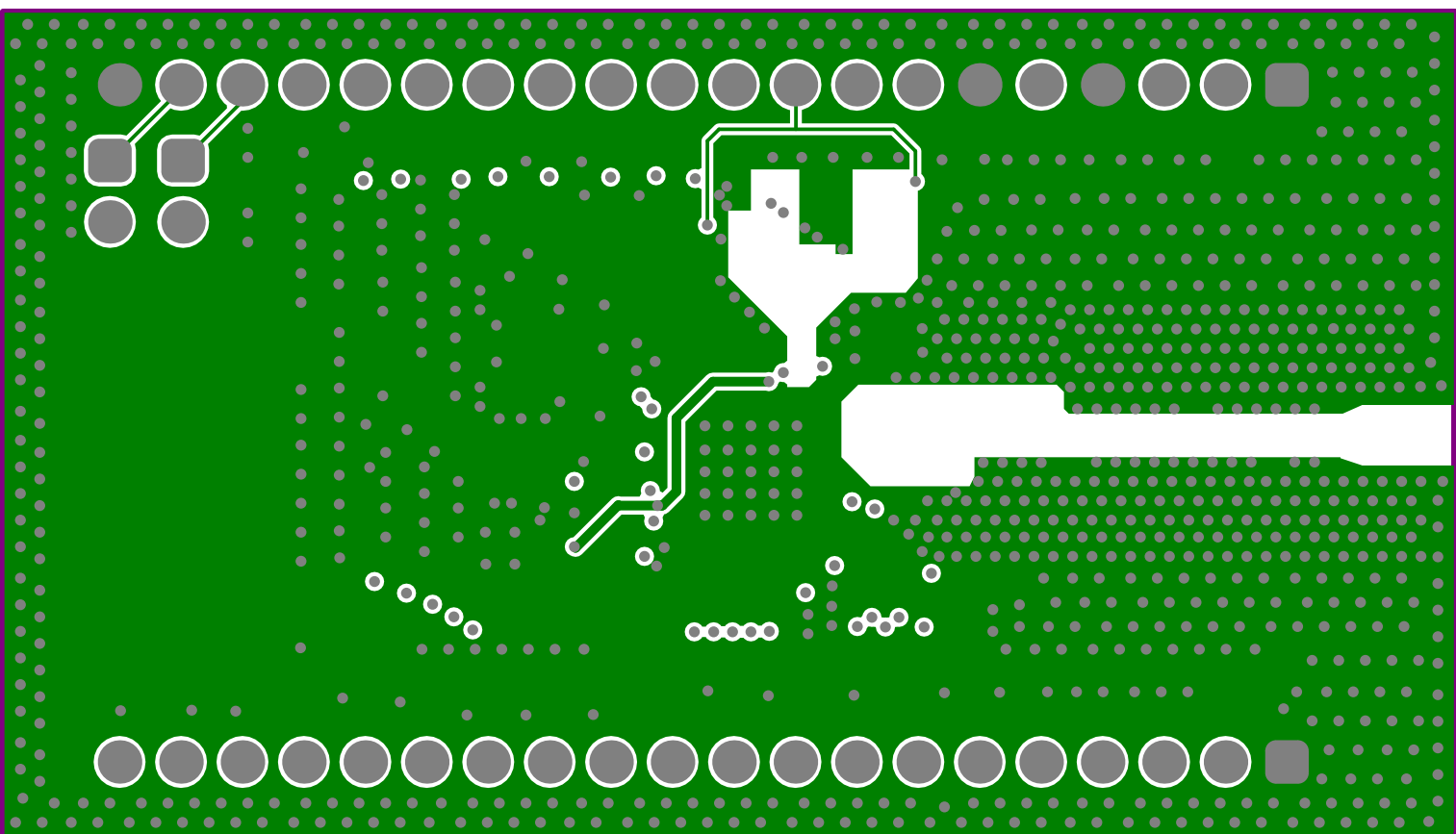



Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	

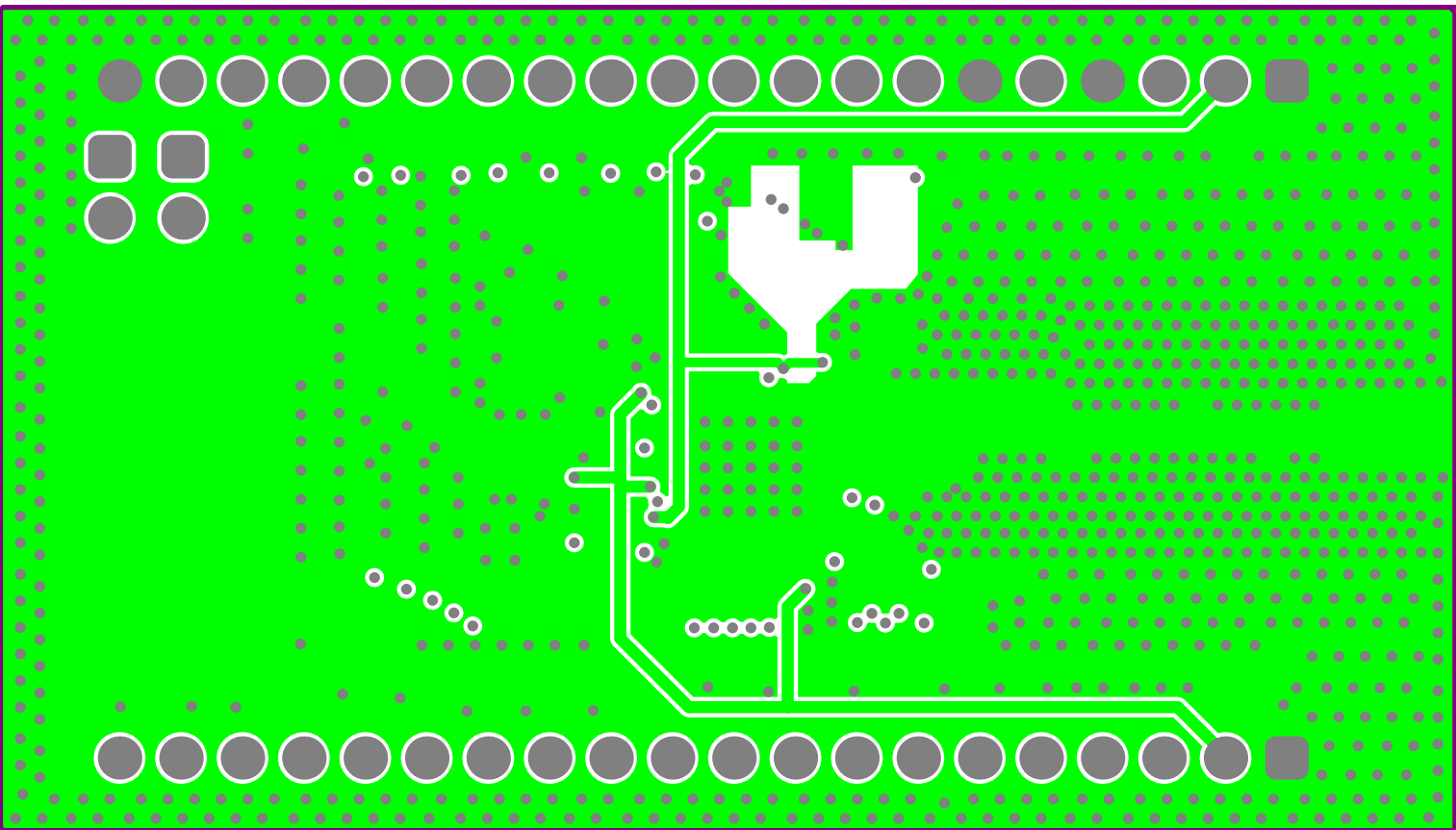
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.79mil	3.7	
1	Top Layer	Copper	1.38mil		
	Dielectric 1	1x106 + 1x2116	6.30mil	3.7	
2	Mid-Layer 1	Copper	1.38mil		
	Dielectric2	FR-4	24.02mil	5	
3	Mid-Layer 2	Copper	1.38mil		
	Dielectric3	1x106 + 1x2116	6.30mil	3.7	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.79mil	3.7	
	Bottom Overlay				




Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	



Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Mid-Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	



Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Mid-Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	



Project: STM32WL_QFN48_HP_DirectTie_RefBoard

Layer: [Bottom Layer](#)

Gerber: [.GBL](#)

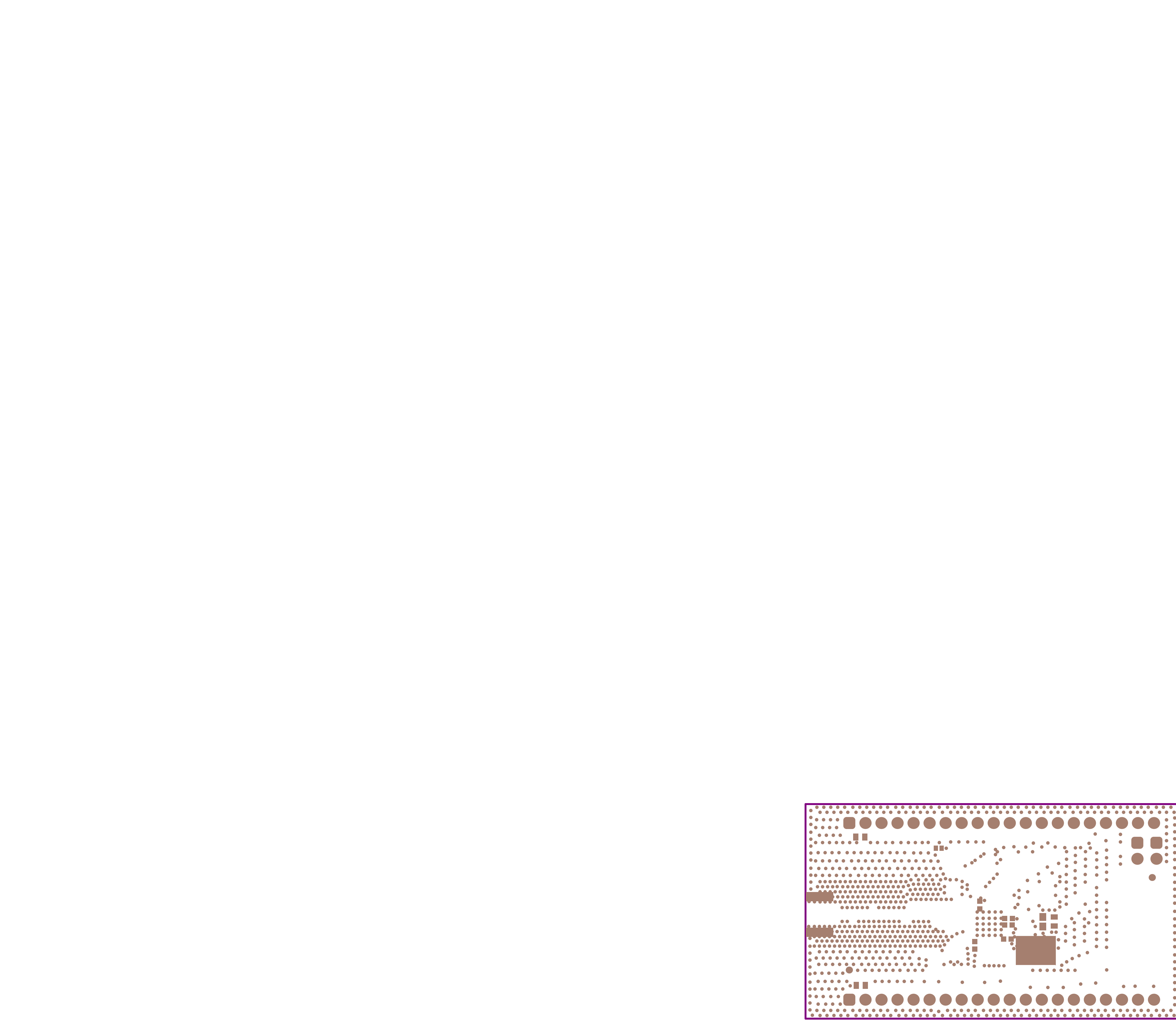
Variant: [No Variations]

Ref: MB1789_HP

Date: 04-04-2022

Rev: A





Project: STM32WL_QFN48_HP_DirectTie_RefBoard

Layer: Bottom Solder

Gerber:.GBS

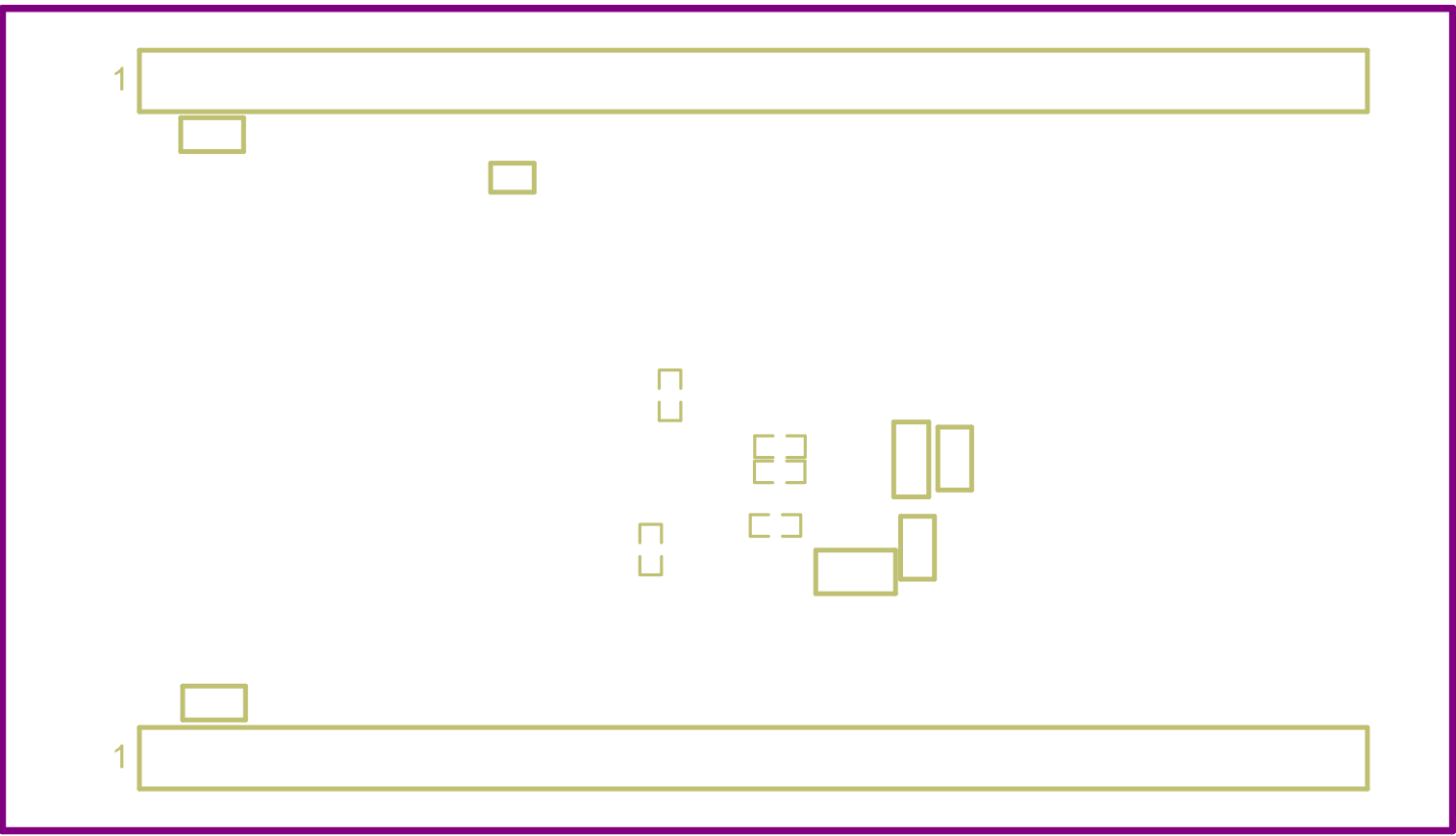
Variant: [No Variations]

Ref: MB1789_HP

Date: 04-04-2022

Rev: A





Project: STM32WL_QFN48_HP_DirectTie_RefBoard

Layer: Bottom Overlay

Gerber:.GBO

Variant: [No Variations]

Ref: MB1789_HP

Date: 04-04-2022

Rev: A



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description
▽	990	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v45h20	
□	44	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	
	1034 Total								

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	27.6	7.28	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☒ GREEN

☐ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

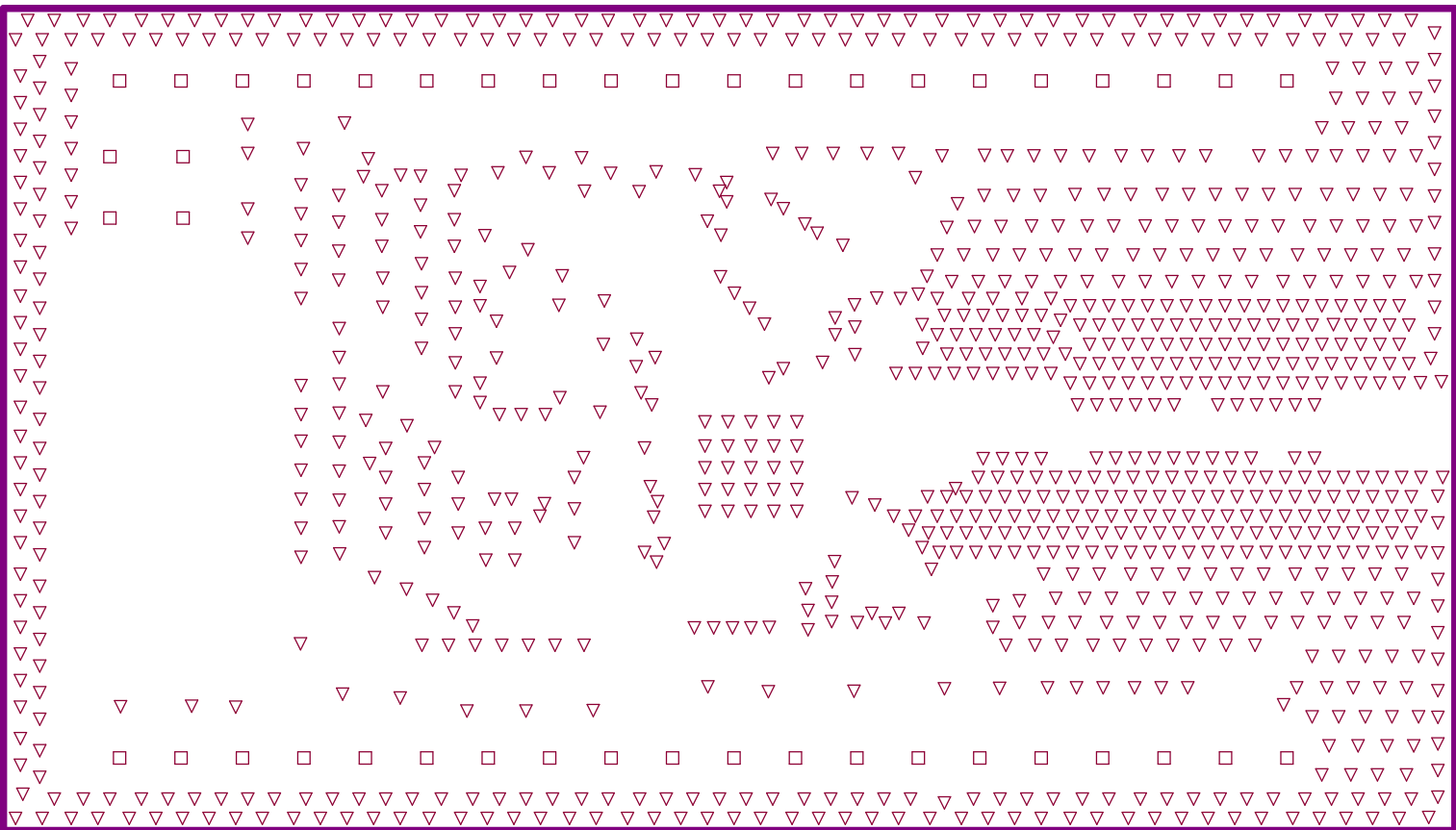
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.


PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1789_HP	
Date: 04-04-2022	Rev: A	